



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

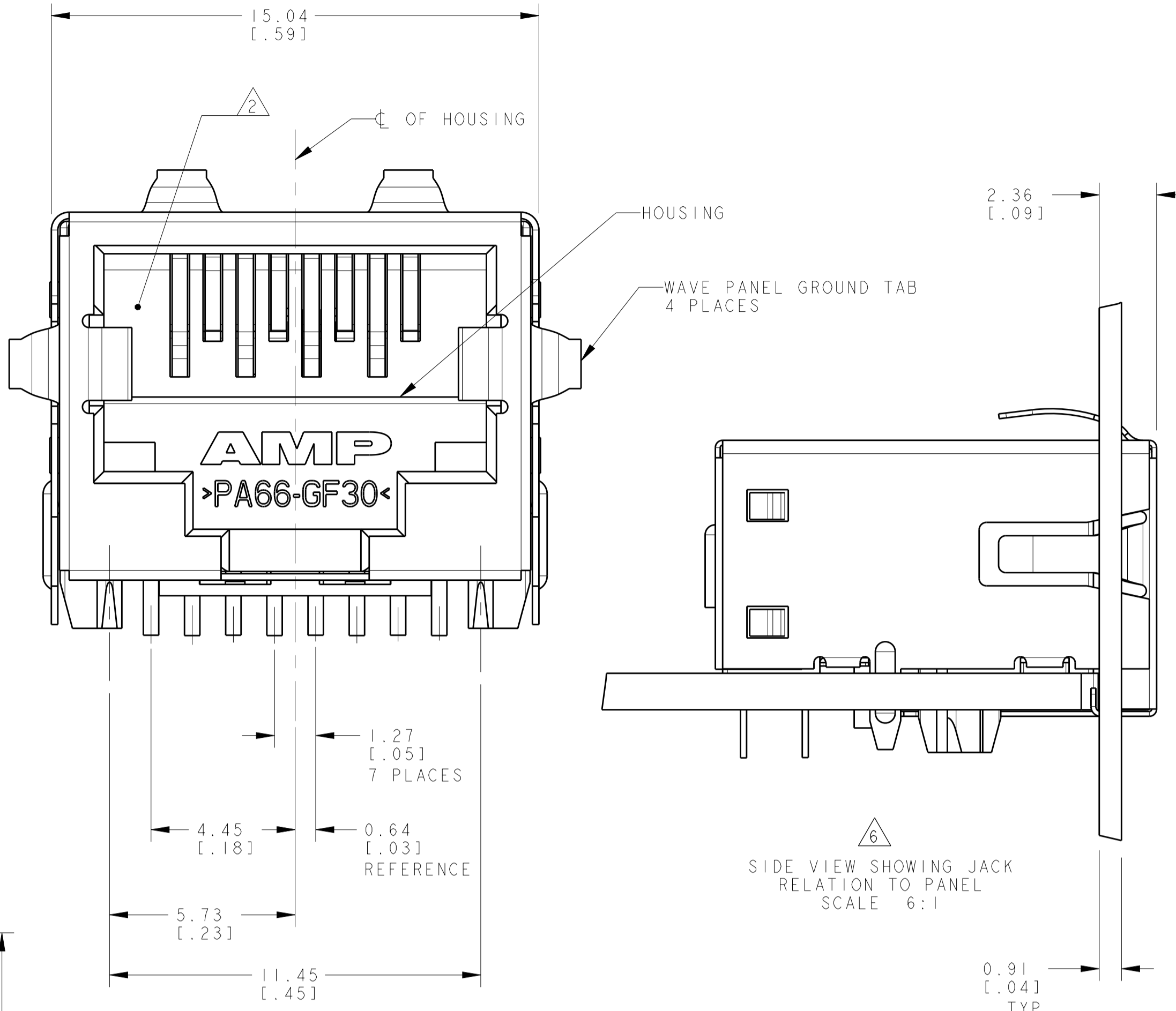
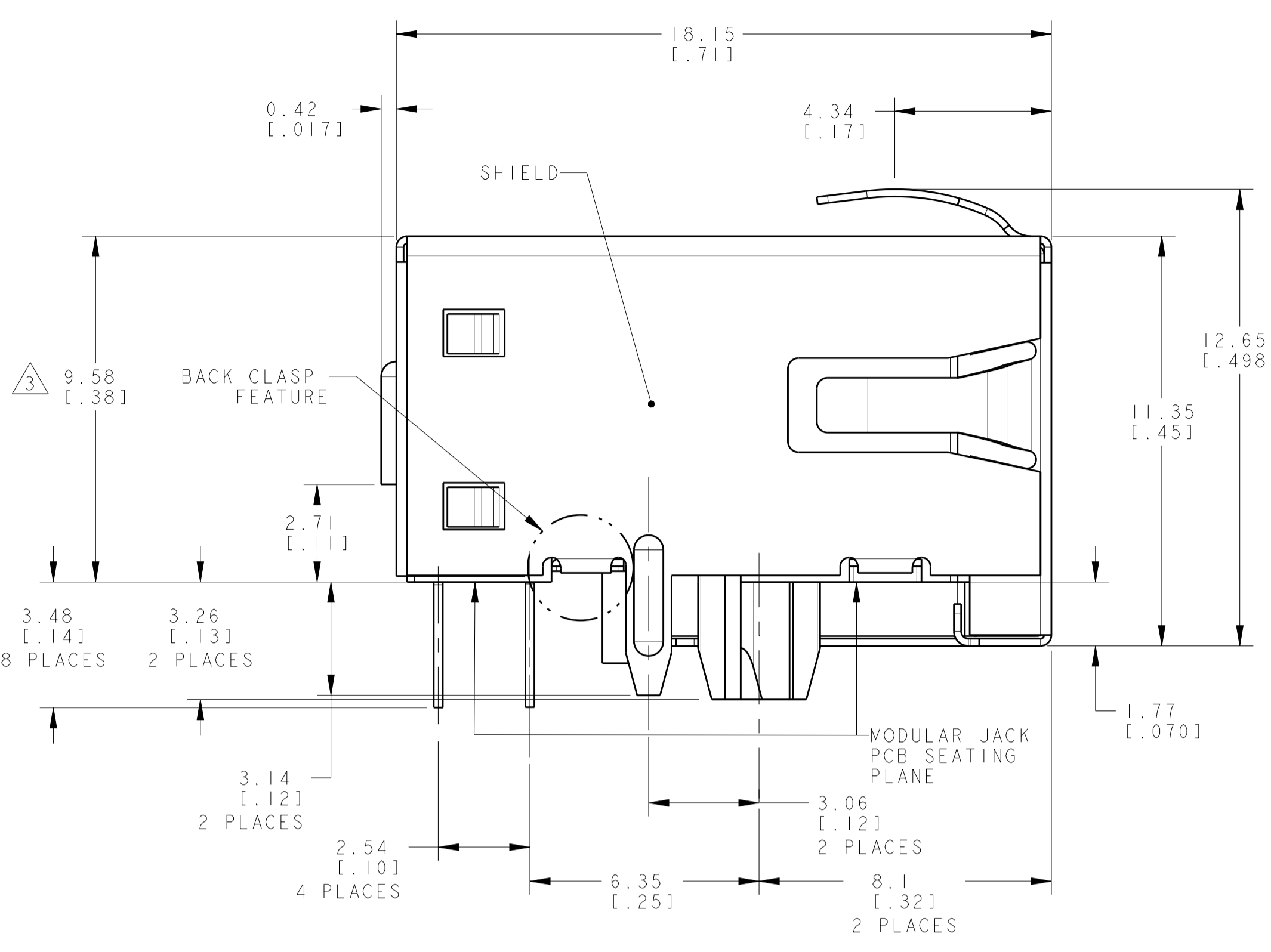
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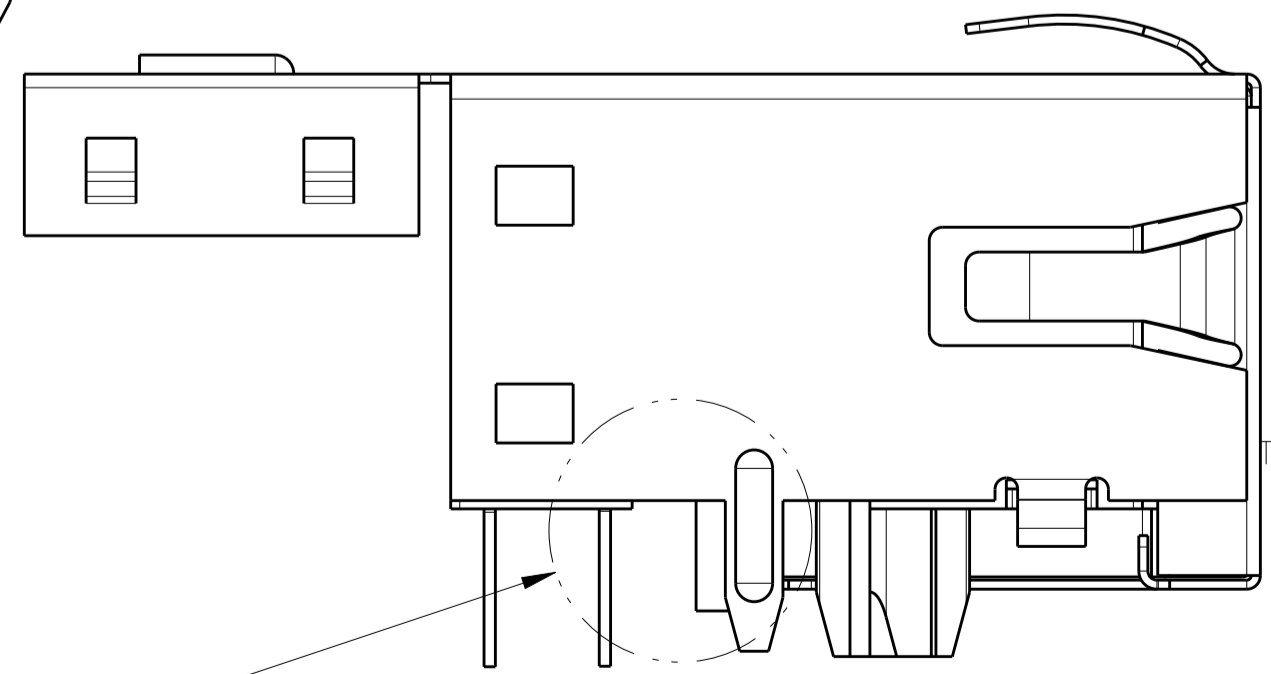
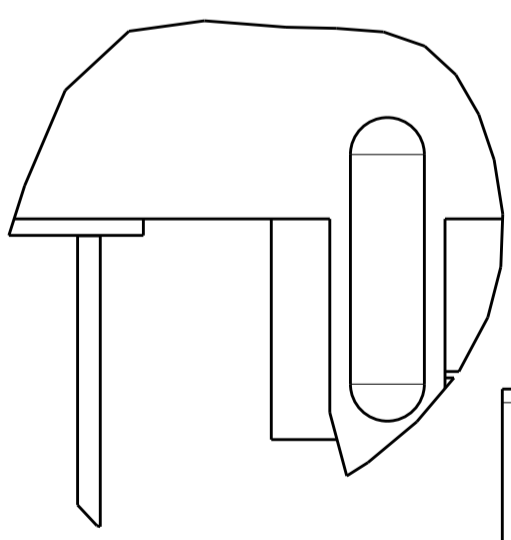
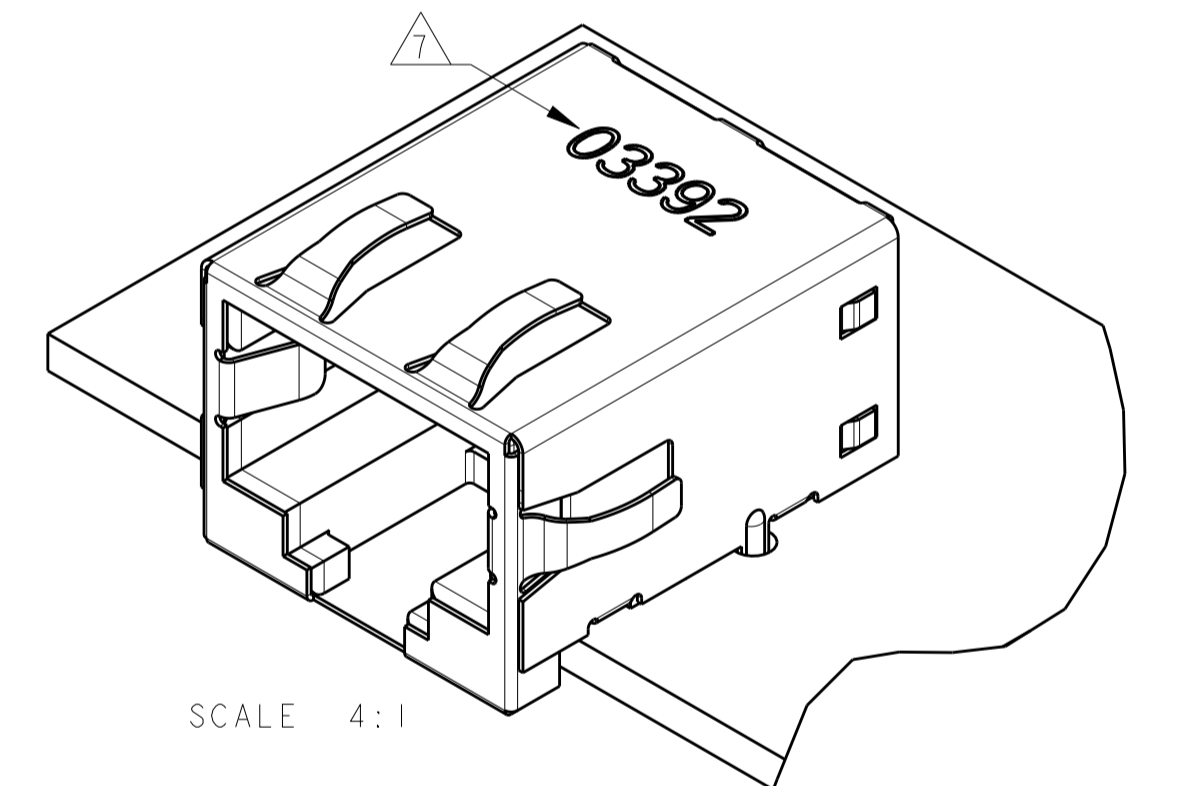
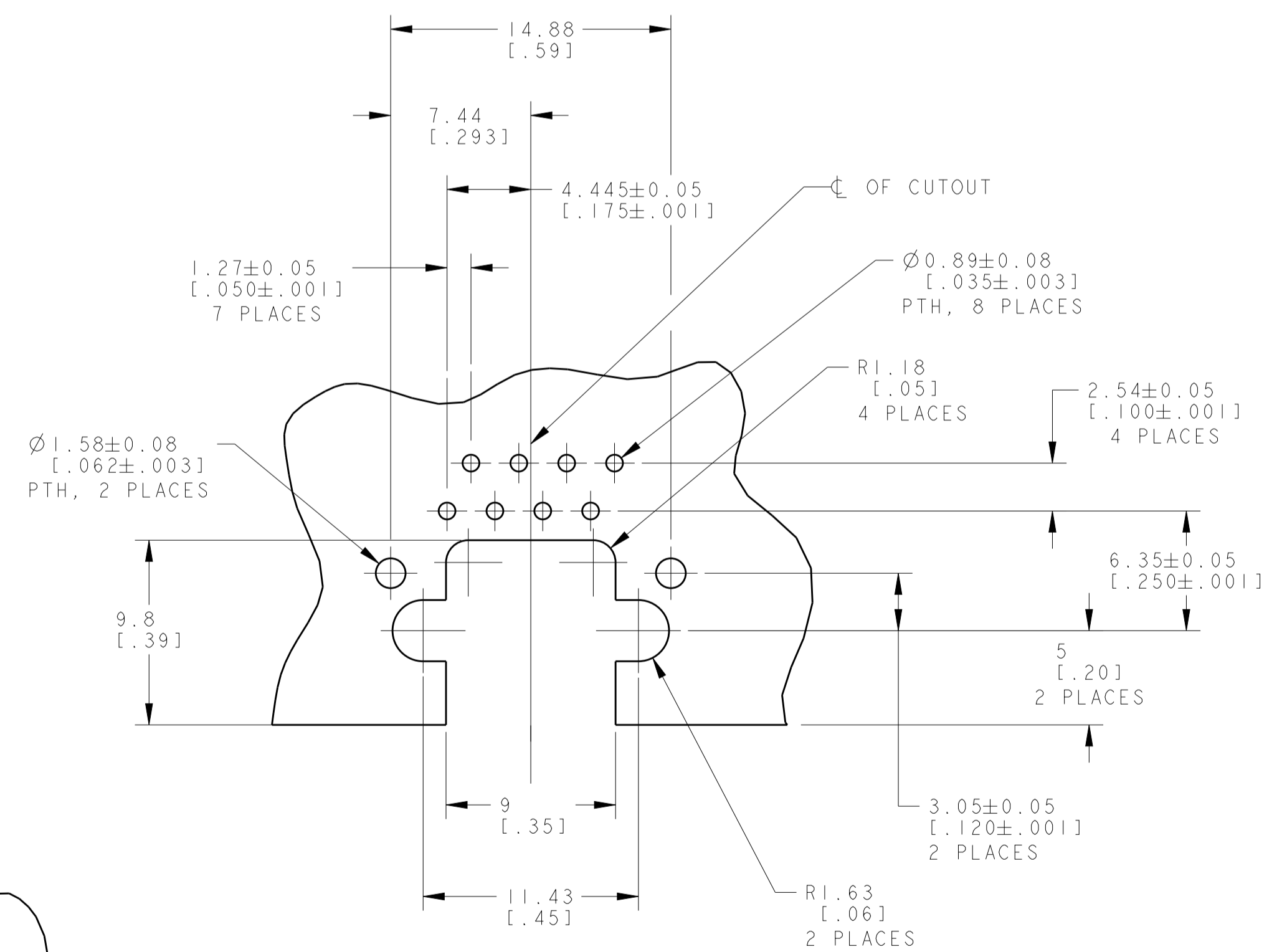
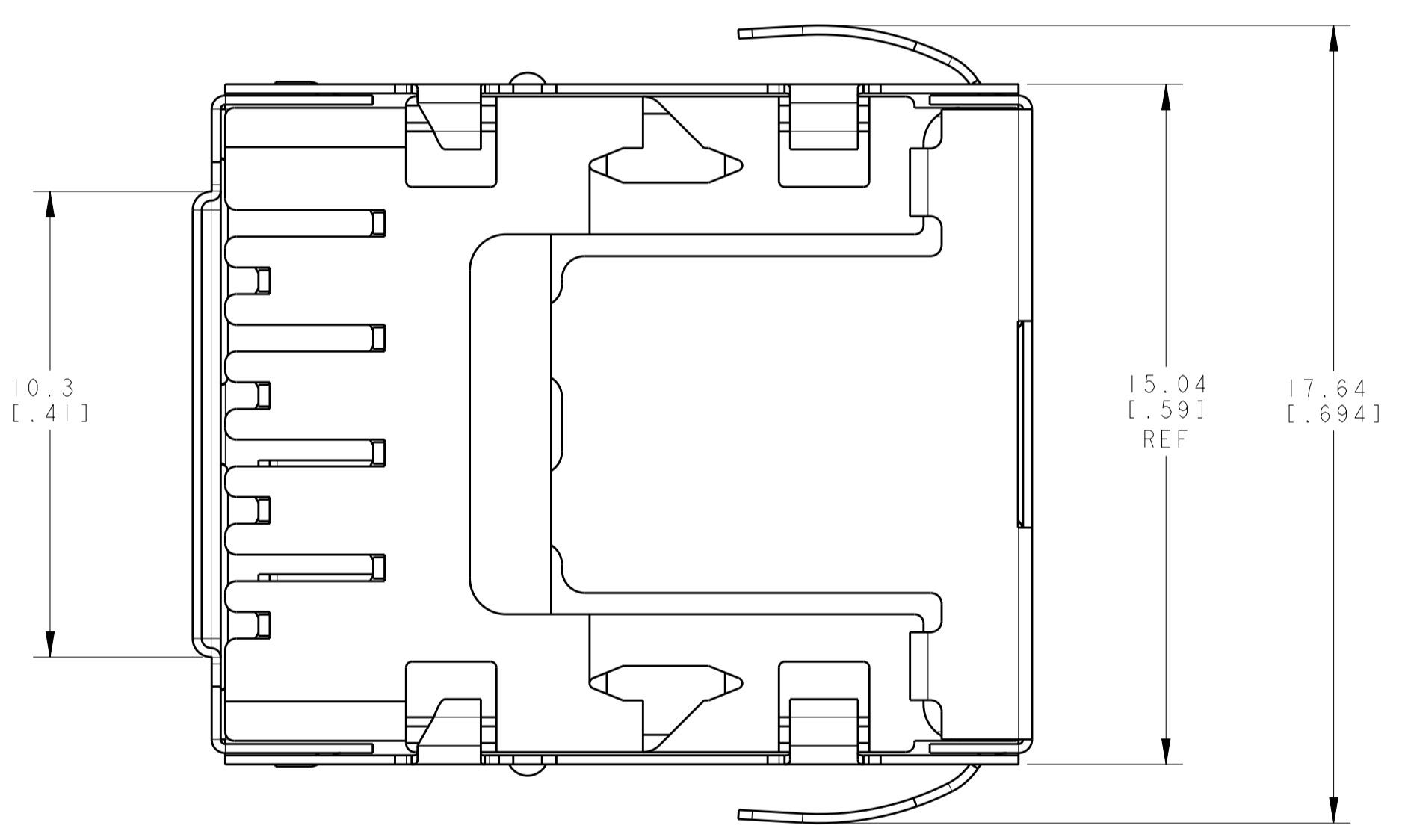
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



REVISIONS				
P.	LTN.	DESCRIPTION	DATE	APPV.
C		REVISE PER ECO-14-015233	27APR2015	LL SH



- 1. MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0 TERMINALS - 0.25(.01) THICK PHOS BRONZE PLATED WITH 3.81µm(.000150) MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27µm(.000050) MINIMUM GOLD IN LOCALIZED PLATE AREA, ENTIRE TERMINAL PLATED WITH 1.27µm(.000050) MINIMUM THICK NICKEL. SHIELD - 0.1(.0039) MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 2.0-4.0 µm (.000079-.000157) THICK BRIGHT TIN OVER 1.27 µm (.000050) MIN. THICK NICKEL.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- 3. THIS DIMENSION REPRESENTS THE TOTAL HEIGHT OF THE CONNECTOR FROM THE TOP OF THE PC BOARD.
- 4. PACKAGED 66 ASSEMBLIES PER PVC TRAY, XX PER BOX.
- 5. DIELECTRIC WITHSTANDING VOLTAGE BETWEEN SHIELD AND CONTACT IS 1500 VAC (RMS) PER IEEE 802.3.
- 6. SEE TYCO PN 1116062-1 FOR IEEE 1386 MEZZANINE PCI CARD APPLICATIONS. PN 1658869-1 IS NOT COMPATIBLE WITH IEEE 1386 BEZEL.
- 7. MANUFACTURING DATE CODE: ORIENTED AND LOCATED APPROXIMATELY AS SHOWN. LASER PRINTING. TEXT HEIGHT APPROX. 2MM. FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR NEXT 2 DIGITS = MANUFACTURING WORK WEEK LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1
- 8. MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0 TERMINALS - 0.25(.01) THICK PHOS BRONZE PLATED WITH 3.81µm(.000150) MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27µm(.000050) MINIMUM GOLD IN LOCALIZED PLATE AREA, ENTIRE TERMINAL PLATED WITH 1.27µm(.000050) MINIMUM THICK NICKEL. SHIELD - 0.1(.0039) MIN THICK COPPER ZINC ALLOY, PLATED WITH 1.27 µm (.000050) MIN. THICK NICKEL AND 2.03 µm (.000080) MIN. THICK HOT TIN DIP ON PCB GROUND TABS.



SCALE 6:1  
 P/N: 1888542-3  
 FEATURE SAME AS 1888542-2  
 EXCEPT AS SHOWN WITHOUT  
 BACK CLASP FEATURE

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: 01JUNE2006 BRIAN KUHLVIZ & MAYER		DRAWN: 01JUNE2006 S. ELICKINGERA	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME: MODULAR JACK ASSEMBLY, 8 POSITION, SHIELDED, 10mm, WAVE PANEL GROUND TABS	
0 PLC ±		1 PLC ±		PRODUCT SPEC: 108-1163	
2 PLC ±		3 PLC ±		APPLICATION SPEC: 114-2048	
4 PLC ±		ANGLES ±		SIZE: 114-2048	
MATERIAL: SEE TABLE		FINISH: SEE TABLE		WEIGHT: 3.49 grams	
				CUSTOMER DRAWING	
				SCALE: 3:1 SHEET 1 OF 1 REV C	

8	1888542-3
7	1888542-2
MATERIAL / FINISH	PART NUMBER

